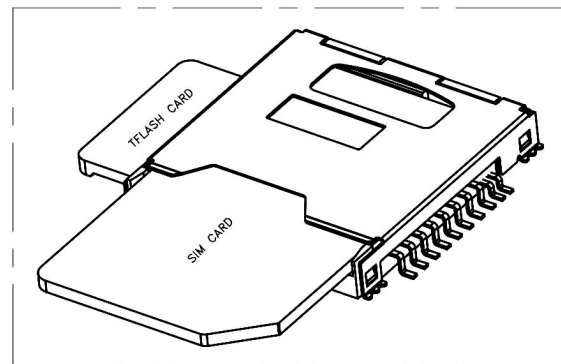


Note:

- 1) MATERIAL:  
 INSULATOR: HIGHT TEMP THERMOPLASTIC, UL94V-0 RATED, BLACK  
 Contacts: PhosPhor Bronze  
 Shell: SUS
- 2) PLATING:  
 Contact Terminal:  
 Base: Ni Plating 50u" Min.  
 Contact Area: Au plating (Gold flash).  
 Solder area: Sn plating 80u" Min.  
 Shell:  
 Base: Ni Plating 50u" Min.  
 Solder area: Au plating 3u" (Gold flash).
- 3) ELECTRICAL:  
 Operation voltage: 3.3 VAC.  
 Current rating: 0.5 Amps max.  
 Contact resistance: 40 mohms initial  
 Insulation resistance: 1000 Mohms min @ 500 VDC  
 Dielectric withstanding voltage: 250 VAC / minute  
 Operating temperature: -20°C TO +80  
 Mating cycles: 10,000 insertions(Mirco SD Card)



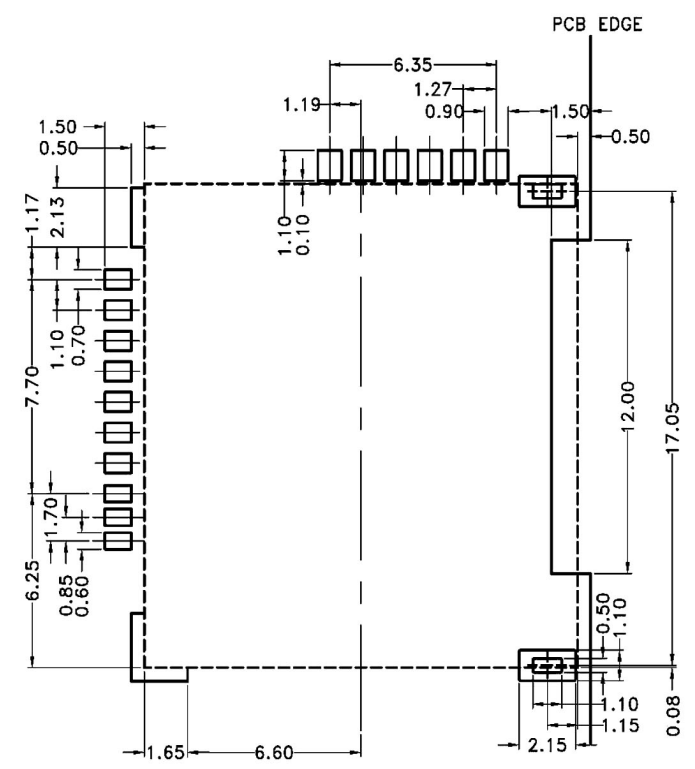
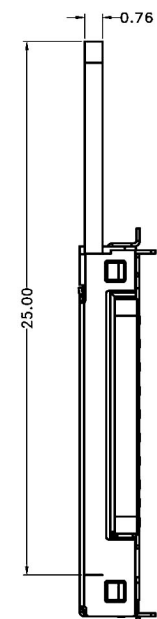
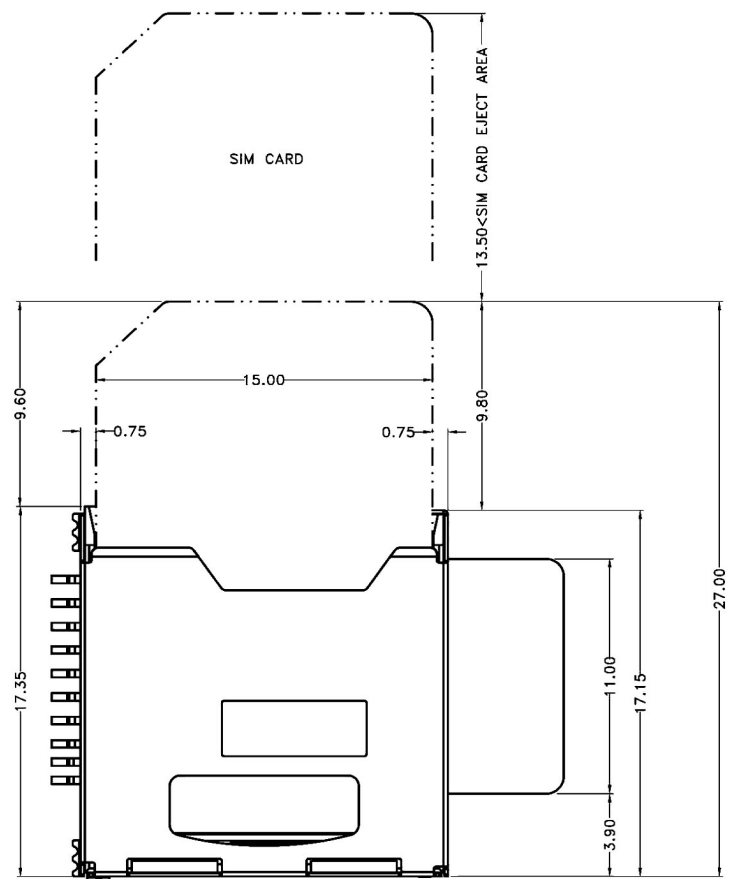
Customer Drawing

RoHS Compliant		HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准 Betty	SCALE 比例 參考	TOLERANCE 容許公差 .0 ± 0.25 .00 ± 0.15 ANG. ± 0.5°	PART NAME 品名 TFLASH+SIM CARD SMT TYPE 16P SELECTIVE GOLD 3U" PLATING BLACK COLOR REEL PACKING ROHS
DWG. 製圖 Betty	UNIT 單位 MM	SIZE. 紙張尺寸 A 4	PART NO. 料號 C0633-16DPBR00R
DATE 制表日 2013/11/15	PAGE 張數 1 OF 2	REV. 版次 A	

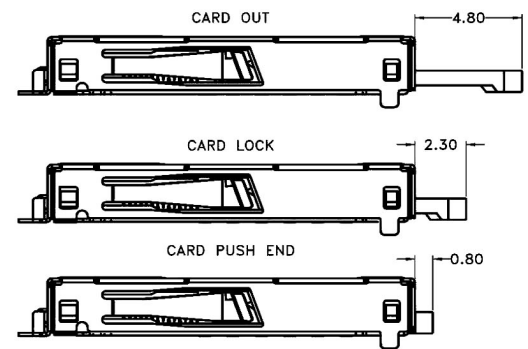
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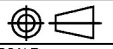
A  
B  
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G  
H



RECOMMENDED PCB



APPD. 核准 Betty		 TOLERANCE 容許公差 .0 ± 0.25 .00 ± 0.15 ANG. ± 0.5°	PART NAME 品名 TFLASH+SIM CARD SMT TYPE 16P SELECTIVE GOLD 3U" PLATING BLACK COLOR REEL PACKING ROHS
DWG. 製圖 Betty			
DATE 制表日 2013/11/15		SCALE 比例 參考 UNIT 單位 M M PAGE 張數 2 OF 2	PART NO. 料號 C0633-16DPBR00R

RoHS Compliant **HSM** 玄茂科技股份有限公司  
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1 2 3 4 5 6 7 8